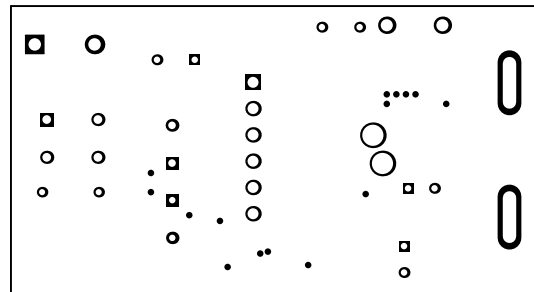
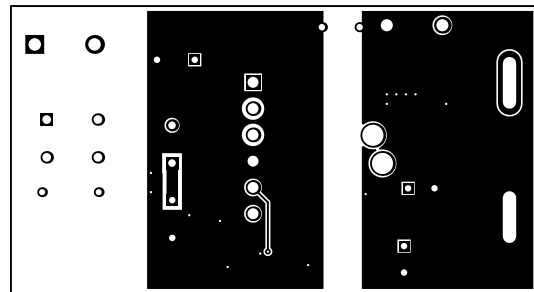


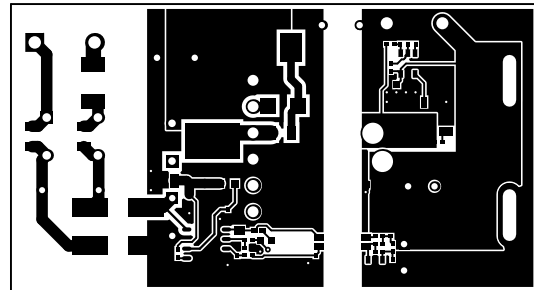
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 5/14/2017 5:12:34 PM	TEXAS INSTRUMENTS	



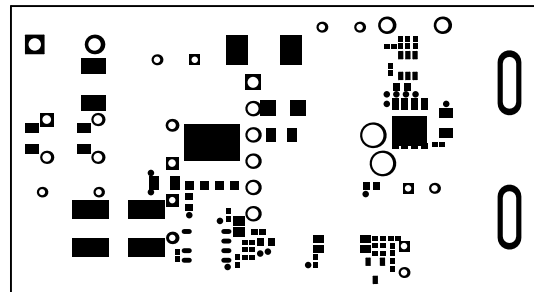
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 5/14/2017 5:12:35 PM	TEXAS INSTRUMENTS	



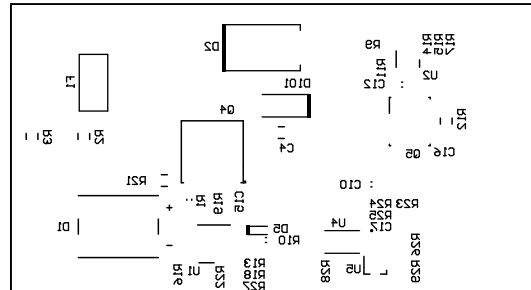
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 5/14/2017 5:12:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 5/14/2017 5:12:37 PM	TEXAS INSTRUMENTS	



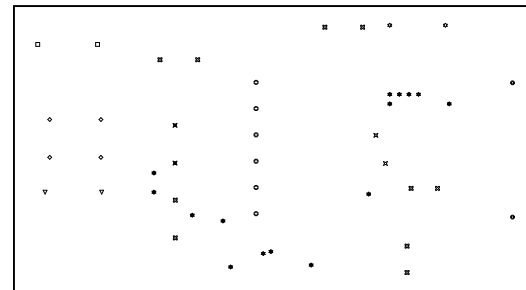
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/14/2017 5:12:38 PM	TEXAS INSTRUMENTS	



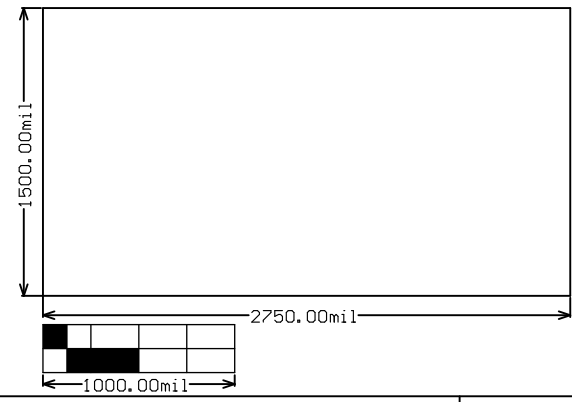
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 5/14/2017 5:12:39 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✳	15	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	10	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
✕	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	6	57.09mil (1.450mm)	PTH	Round	Top Layer - Bottom Layer	
☆	2	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	64.96mil (1.650mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	110.24mil (2.800mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	2	70.00mil (1.778mm)	PTH	Slot	Top Layer - Bottom Layer	
	47 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 5/14/2017 5:12:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11372	REV: C	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 5/14/2017 5:12:41 PM	TEXAS INSTRUMENTS	

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